

# **HANDBOOK OF MULTILEVEL METALLIZATION FOR INTEGRATED CIRCUITS**

## **Materials, Technology, and Applications**

Edited by

**Syd R. Wilson**

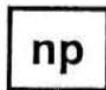
and

**Clarence J. Tracy**

Materials Research Organization  
Motorola Semiconductor Products Sector  
Mesa, Arizona

**John L. Freeman, Jr.**

Advanced Custom Technologies  
Motorola Semiconductor Products Sector  
Mesa, Arizona



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